

Semiconductor devices — Mechanical and climatic test methods —

Part 22: Bond strength

The European Standard EN 60749-22:2003 has the status of a
British Standard

ICS 31.080.01

National foreword

This British Standard is the official English language version of EN 60749-22:2003. It is identical with IEC 60749-22:2002. It partially supersedes BS EN 60749:1999 which will be withdrawn on 2005-10-01.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, which has the responsibility to:

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Summary of pages

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Amendments issued since publication

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